

UP Storage SuperServer SSG-110P-NTR10



Key Applications

Virtualization
 Cloud Computing
 All Flash Storage
 CDN Optimized

Key Features

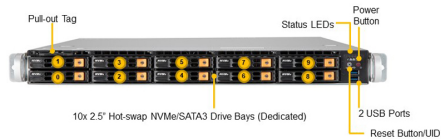
- Single Socket P+ (LGA-4189) 3rd Gen Intel® Xeon® Scalable processors. Up to 270W TDP.;
- 8 DIMMs; Supports 3DS DDR4-3200: RDIMM/LRDIMM/Intel® DCPMM;
- 1 PCI-E 4.0 x16 (FHHL) slot;
- Intel® Ethernet Controller X550 2x 10GbE RJ45;
- 10x Hot-swap 2.5" All NVMe Gen 4 tool-less drive bays; Onboard 2x NVMe Gen 3/SATA M.2;
- Redundant Platinum 860W Power Supply;

[More details here](#)

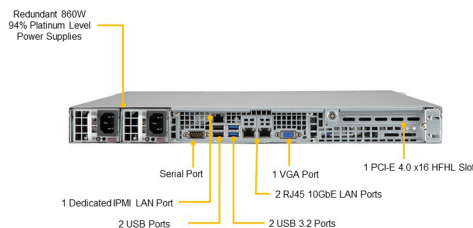


Form Factor	1U Rackmount Enclosure: 437 x 43 x 597mm (17.2" x 1.7" x 23.5") Package: 610 x 203 x 813mm (24" x 8" x 32")
Processor	Support Intel® 3rd Gen Xeon® Scalable Processors Single Socket LGA 4189 (Socket P+) supported TDP up to 270W;
System Memory	8 DIMM slots ECC RDIMM, DDR4-3200MHz ECC LRDIMM, DDR4-3200MHz Intel® DCPMM, DDR4-3200MHz
Drive Bays	10x 2.5" hot-swap NVMe drive bays;
Expansion Slots	Slot 1: PCI-E 4.0 x16 FHHL
On-Board Devices	NVMe: NVMe Gen 4 via MB onboard controller; RAID 0, 1, 5, 10 support (with additional VROC module) Chipset: Intel® C621A Network Connectivity: 2x 10GbE BaseT with Intel® X550 IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 RJ45 Dedicated IPMI LAN port 2 RJ45 10GBase-T LAN ports USB: 5 USB 3.2 Gen 1 port(s) (2 front; 2 rear; 1 Type A) 4 USB 2.0 port(s) (2 rear; 2 headers) Video: 1 VGA port(s) Serial Port: 2 COM Port(s) (1 header; 1 rear) DOM: 2 SuperDOM (Disk on Module) port with built-in power

(Front View – System)



(Rear View – System)



Cooling System	6x (4cm x 4cm x 5.6cm) heavy duty fan(s)
Power Supply	AC 860W, Platinum Level, Redundant Power Supply, 54.5mm width Dimension (W x H x L): 54.5 x 40.25 x 320 mm Output Type: Gold Finger
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
Management	NMI; SUM; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; Redfish API; IPMI2.0
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory 7+1 Phase-switching voltage regulator module (VRM) FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Height: 1.7" (43 mm) Width: 17.2" (437 mm) Depth: 23.5" (597 mm) Gross Weight: 38 lbs (17.24 kg) Net Weight: 25 lbs (11.34 kg) Packaging: 8" (H) x 24" (W) x 32" (D) Available Color: Black
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X12SPO-NTF
Chassis	CSE-116TS-R860CBP-N10

Parts List - (Items Included)

	Part Number	Qty	Description
Motherboard / Chassis	MBD-X12SPO-NTF	1	Super X12SPO-NTF Motherboard
	CSE-116TS-R860CBP-N10	1	1U Chassis
Backplane	BPN-SAS3-LB16A-N10	1	1U 10-Slot SFF Hybrid Backplane Supports 10xSAS3/SATA3/NVMe4 Storage Devices with 1x(2x4) + 2x(1x4) + 1x(2x2) Power Connectors
Cable 1	CBL-0062L	1	12V 8 TO 8 PIN POWER CONNECTOR EXTENSION, LF
Cable 2	CBL-SAST-1231-85	1	Slimline x8 (STR) to Slimline x8 (STR),INT,30CM, 85 OHM
Cable 3	CBL-SAST-1267-85	4	Slimline x8 (STR) to Slimline x8 (STR),INT,67CM,85 OHM,
FAN 1	FAN-0141L4	2	40x40x56 mm 20.5K RPM / 17.6K RPM Counter-rotating Fan
Manual	MNL-2366-QRG	1	110P-NTR10 Quick Reference Guide
Riser Card	RSC-S-6G4	1	1U LHS Standard riser card with one PCI-E 4.0 x16 slot,HF,Ro
Software	SFT-OOB-LIC	1	License key for enabling OOB BIOS management
Heatsink / Retention	SNK-P0077P	1	1U Passive CPU Heat Sink for X12 Generation Intel Whitley and Cedar Island Platforms
*Power Supply	PWS-860P-1R2	2	1U 860W, Redundant power supply, 54.5mm width, Platinum with
*Power Distributor	PDB-PT112-2424	1	SC112 24PIN REDUNDANT PWS DISTRIBUTOR
*Cable 4	CBL-0335L	1	FRONT CTL CABLE 20 PIN TO 20 PIN W/TUBE,70CM,PBF
*Cable 5	CBL-PWCD-0160-IS	2	PWCD,US,NEMA5-15P TO IEC60320 C13,6FT,16AWG,RoHS/REACH
*FAN 2	FAN-0141L4	4	40x40x56 mm 20.5K RPM / 17.6K RPM Counter-rotating Fan
*Front Panel	FPB-FP116-DU3	1	Front control board with two USB 3.0 for SC116/SC119X
*Drive Tray(s)	MCP-220-00167-0B	10	Gen 3 2.5-inch Tool-less NVMe drive tray (clip design),RoHS
*Rear Window	MCP-240-00086-0N	1	STD rear window for SC113 redundant PWS
*Power Supply	MCP-250-00009-0N	1	SC113 Redundant Power Distributor Cover
*Parts	MCP-260-00078-0N	1	1U I/O shield for X10 and X9 Server MB with 5X5mm vent hole and EMI Gasket,RoHS/REACH,PBF
*Rail Set	MCP-290-00063-0N	1 set	Rail set, quick/quick, default for 1U 17.2"W for SC113/SC116,RoHS/REACH
*Air Shroud	MCP-310-19002-0N	1	SC815/113/116 Intel DP X9, X8 PC air shroud, 12x13MB
*Fan Holder	MCP-320-00027-0B	24	Plastic pin for 40x28, 40x56 fan
*Fan Holder	MCP-320-00028-0B	1	Fan holder for 6pcs 40x56 fan, assemble-able for SC819/SC119/SC818/SC116
*Fan Holder	MCP-340-00035-0B	2	Dummy fan 40x56mm for 40x56 counter-rotating fan (cost-effective)

Notes:

- Parts with * are inside the chassis
- Excessive parts might not be shipped, including but not limited to excessive drive trays, fans, riser brackets, air shrouds, IO shields, cables.....etc.

Optional Parts List

	Part Number	Qty	Description
Inlet Thermal Sensor	MCP-280-00033-0N	1	Universal Thermal sensor kit with 80cm I2C cable
Intel VROC RAID Key for NVMe	<u>AOC-VROCPREMOD</u>	1	Premium Upgrade module (Intel + 3rd party Vendor SSD); RAID 0/1/10/5
	<u>AOC-VROCSTNMOD</u>	1	Standard Upgrade module (Intel + 3rd party Vendor SSD); RAID 0/1/10
	<u>AOC-VROCINTMOD</u>	1	Intel SSD Only Upgrade module; RAID 0/1/10/5
Software	SFT-DCMS-Single	1	DataCenter Management Package (per node license)
TPM	AOM-TPM-9671H-O	1	TPM 1.2, horizontal form factor, provisioned for server
	AOM-TPM-9670H-O	1	TPM 2.0, horizontal form factor, provisioned for server